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Dynamic Search: INPADOC/Family and Legal Status, JAPIO -Patent Abstracts of Japan, Derwent World Patents Index

Records for: PN=JP 4345015

save as alert...

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Output

Format:

Long

Output as:

Browser

display/send

Modify

refine search

back to picklist

select
all none

Records 1-3 of 3 In long Format

☐ 1. 2/34/1 (Item 1 from file: 351)

009321701

WPI Acc No: 1993-015165/ 199302

Removal of resist pattern film - involves layering a hardening pressure sensitive adhesive layer on a base sheet which is then hardened, and stripping adhesive sheet and resist pattern film

Patent Assignee: HITACHI LTD (HITA); MITSUI CONSTR CO LTD (MITL)

Number of Countries: 001 Number of Patents: 002

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 4345015	A	19921201	JP 91146945	A	19910522	199302 B
JP 3040007	B2	20000508	JP 91146945	A	19910522	200027

Priority Applications (No Type Date): JP 91146945 A 19910522

Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
JP 4345015	A		5	H01L-021/027	
JP 3040007	B2		5	H01L-021/027	Previous Publ. patent JP 4345015

Abstract (Basic): JP 4345015 A

Resist pattern film on a substrate is removed by (1) having a hardening type pressure sensitive adhesive layer of an adhesive sheet consisting of a base sheet and the hardening type pressure sensitive adhesive layer formed on the base sheet, onto the resist pattern film on the substrate, (2) hardening the adhesive layer, and then (3) stripping the adhesive sheet and the resist pattern film from the substrate.

Pref. the base sheet of the adhesive sheet e.g. consists of polyethylene, polypropylene or PET having a thickness of 12-100 micron m. The hardening type pressure sensitive adhesive is e.g. compsn. of acrylic polymer and urethane acrylate.

USE/ADVANTAGE - Resist pattern film on a substrate can be removed from the substrate surface in a short time without contaminating the substrate e.g. composed of a semiconductor wafer with impurity ions often seen in conventional removal method in which solvent or ashing process is u

Dwg.0/0

Derwent Class: A89; G06; L03; P84; U11

International Patent Class (Main): H01L-021/027

International Patent Class (Additional): C09J-005/00; C09J-007/02; C09J-011/06; G03F-007/42; H05K-003/06

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☐ 2. 2/34/2 (Item 2 from file: 347)

03979915 RESIST REMOVING METHOD AS WELL AS PRESSURE SENSITIVE

ADHESIVE AND ADHESIVE SHEET, ETC., APPLICABLE TO THE SAME

Pub. No.: 04-345015 [JP 4345015 A]

Published: December 01, 1992 (19921201)

Inventor: MOROISHI YUTAKA

SUNAKAWA MAKOTO

KAWANISHI MICHIO

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Applicant: NITTO DENKO CORP [000396] (A Japanese Company or Corporation), JP (Japan)

HITACHI LTD [000510] (A Japanese Company or Corporation), JP (Japan)

Application No.: 03-146945 [JP 91146945]

Filed: May 22, 1991 (19910522)

International Class: [5] H01L-021/027; C09J-005/00; C09J-007/02;
C09J-007/02; C09J-011/06; G03F-007/42; H05K-003/06

JAPIO Class: 42.2 (ELECTRONICS -- Solid State Components); 14.7
(ORGANIC CHEMISTRY -- Coating Material Adhesives); 29.1 (PRECISION
INSTRUMENTS -- Photography & Cinematography); 42.1 (ELECTRONICS --
Electronic Components)

Journal: Section: E, Section No. 1353, Vol. 17, No. 202, Pg. 80, April 20,
1993 (19930420)

ABSTRACT

PURPOSE: To easily and surely peel of the resist on a useless article during the manufacturing step of a semiconductor and the circuit making step.

CONSTITUTION: An adhesive sheet, etc., using the title pressure sensitive adhesive having excellent affinity to a resist material is affixed on an article having a resist pattern thereon and then the adhesive sheet, etc., and the resist material are peeled of all together after setting said adhesive.

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☐ 3.

2/34/3 (Item 3 from file: 345)

.10908295

Basic Patent (No,Kind,Date): JP 4345015 A2 19921201

PATENT FAMILY:

JAPAN (JP)

Patent (No,Kind,Date): JP 4345015 A2 19921201

RESIST REMOVING METHOD AS WELL AS PRESSURE SENSITIVE ADHESIVE AND
ADHESIVE SHEET, ETC., APPLICABLE TO THE SAME (English)

Patent Assignee: NITTO DENKO CORP; HITACHI LTD

Author (Inventor): MOROISHI YUTAKA; SUNAKAWA MAKOTO; KAWANISHI MICHIO;
MIZUNO FUMIO; MORIUCHI NOBORU

Priority (No,Kind,Date): JP 91146945 A 19910522

Applic (No,Kind,Date): JP 91146945 A 19910522

IPC: * H01L-021/027; C09J-005/00; C09J-007/02; C09J-011/06;
G03F-007/42; H05K-003/06

CA Abstract No: ; 119(04)039137A

Derwent WPI Acc No: ; C 93-015165

JAPIO Reference No: ; 170202E000080

Language of Document: Japanese

Patent (No,Kind,Date): JP 3040007 B2 20000508

Patent Assignee: NITTO DENKO CORP; HITACHI LTD

Author (Inventor): MOROISHI YUTAKA; SUNAKAWA MAKOTO; KAWANISHI MICHIO;
MIZUNO FUMIO; MORIUCHI NOBORU

Priority (No,Kind,Date): JP 91146945 A 19910522

Applic (No,Kind,Date): JP 91146945 A 19910522

IPC: * H01L-021/027; C09J-005/00; C09J-007/02; C09J-011/06;
G03F-007/42; H05K-003/06

Language of Document: Japanese

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